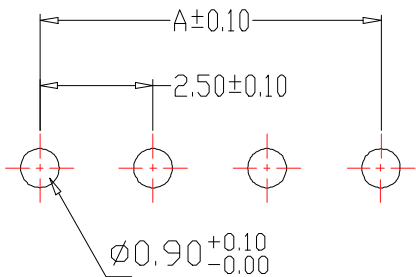
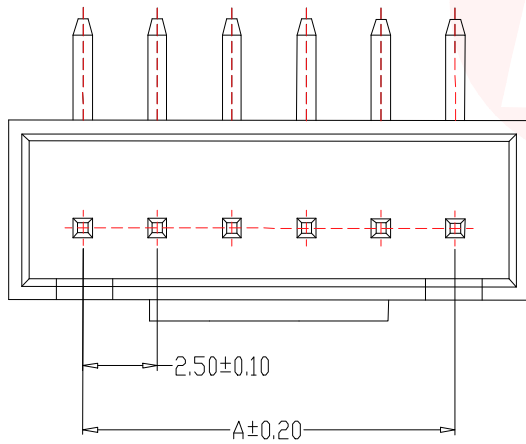
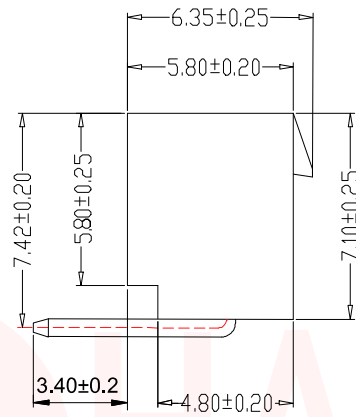
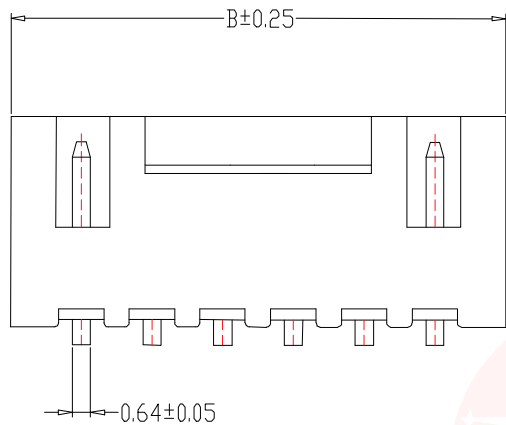




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



PCB LAYOUT

技术要求:

- 1、塑件材料: CM3004 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻: ≤10mΩ
- 4、绝缘电阻: ≥1000MΩ
- 5、额定电压: 250V AC DC
- 6、额定电流: 2.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度: -25° ~ +85°
- 9、可焊性试验: 浸锡面积≥95%温度220⁺⁵₀, 时间 2.5±0.5秒
- 10、铅和镉等六大有害物质含量要符合环保要求

TABLE:

CSG PART NO.	Dimension mm		
	PIN	A	B
WAFER-HA254WZ-2A	2P	2.50	7.50
WAFER-HA254WZ-3A	3P	5.00	10.00
WAFER-HA254WZ-4A	4P	7.50	12.50
WAFER-HA254WZ-5A	5P	10.00	15.00
WAFER-HA254WZ-6A	6P	12.50	17.50
WAFER-HA254WZ-7A	7P	15.00	20.00
WAFER-HA254WZ-8A	8P	17.50	22.50
WAFER-HA254WZ-9A	9P	20.00	25.00
WAFER-HA254WZ-10A	10P	22.50	27.50
WAFER-HA254WZ-11A	11P	25.00	30.00
WAFER-HA254WZ-12A	12P	27.50	32.50
WAFER-HA254WZ-20A	20P	47.50	52.50

2~4A

序号	名称	材料	电镀 (锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	LCP/PA66 (UL94V-0)	白色

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:
 X :±0.20 X :±2°
 X.X :±0.10 X.X :±1°
 X.XX :±0.05

东莞市汉博电子科技有限公司
 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	WAFER HA 2.54MM 弯针 DIP TYPE		
DWN	xiong	PART NO. WAFER-HA254WZ-NA	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
REV: A4			

CUSTOMER COPY